100,00 mm 9,90 mm 8,00 mm 40,00 mm 52,00 mm E 39,00 44,00 52,00 E Ø2 mm Ø 3.2 mm 34,00 mm 30,00 mm 25,00 mm 8,40 mm

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1,5842 mm

Board overall dimensions: 100,0000 mm x 52,0000 mm

Min track/spacing: 0,1000 mm / 0,0000 mm Min hole diameter: 0,2500 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors:

BOARD STACKUP

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0,01 mm	Green	3,3	0
F.Cu	copper		0,035 mm		1	0
Dielectric	prepreg	JLCPCB-3313	0,0994 mm	FR4 natural	4,1	0
In1.Cu	copper		0,0152 mm		1	0
Dielectric	core	FR4	1,265 mm	FR4 natural	4,5	0,02
In2.Cu	copper		0,0152 mm		1	0
Dielectric	prepreg	JLCPCB-3313	0,0994 mm	FR4 natural	4,1	0
B.Cu	copper		0,035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0,01 mm	Green	3,3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

JLCPCB Stackup (JLC04161H-3313)

IMPEDANCE CALCULATIONS

Signal type	Impedance	Trace width	Trace Spacing	Clearance
Single ended (non-coplanar)	50 ohms	5.99 mils (0.152 mm)	-	10 mils (0.254 mm)
Differencial pair (non-coplanar)	100 ohms	5.04 mils (0.128 mm)	9 mils (0.2286 mm)	10 mils (0.254 mm)

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File: som-exp-carrier.kicad_pcb

Title: Experiment Carrier Board Size: A4 Date: 2024-03-26 Rev: v1.0 KiCad E.D.A. 8.0.1 ld: 1/1